

INNODISK APEX SERIES EDGE AI SYSTEMS

















Powered by —



IA |

Qualcomm



Intel

EMPOWERING ENTERPRISE & INDUSTRY EDGE INTELLIGENCE

From the cloud to the edge, AI is evolving. As data grows and decisions move closer to where actions happen, the future of intelligence is no longer centralized—it's distributed, responsive, and real-time.

Cloud AI: Facing Bottlenecks

Al first proved its potential in the cloud, delivering unprecedented computing power and scalability. However, as industries accelerate toward real-world adoption—seeking smarter, faster, and more efficient solutions—new challenges and roadblocks emerge.



Data privacy & security concerns



Latency & cost pressures



Limited flexibility for customization

Edge AI: The Practical Answer

Edge AI brings intelligence closer to where data is generated–scaling down large models to run efficiently at endpoints. It delivers key advantages that overcome the limitations of cloud-based AI, making intelligence more practical, efficient, and widely accessible. Now, the era of Enterprise Edge AI and Industrial Edge AI has truly arrived.



Data security



Reduced cost





Customized intelligence

Customized AI Solutions & One-Stop Integration

Building on the shift from the cloud to the edge, Innodisk delivers comprehensive edge AI systems and flexible product design services—leveraging years of expertise and intelligent building blocks to provide scalable, industrial-grade, and fully compatible solutions.

| 20 YEARS+ | Specialized Industrial Experience | Thermal Engineer | ID Designer / ME | Electronic Engineer | Software Developer (BIOS, FW, OS Driver, AP) | image, |
|-----------|-------------------------------------|-----------------------|------------------------------------|------------------------|---|--|
| 200+ | Dedicated In-House R&D Engineers | Component Engineer | System Architect (x86 / ARM) | DQA Engineer | Project Manager | EMI / Safety Regulatory Engineer |

Innodisk AI Building Blocks

| CLOUD MANAGEMENT | Cloud Al | | iCAP (Innodisk Cloud Administration Platform) | | | | |
|------------------|-------------------|------|---|------------|---------|--------------------------|--|
| SOFTWARE / | iSeries Softwa | are | iSMART / iTracker / iOPAL / iRAID | | | | |
| FIRMWARE | Innodisk AI S | DK | AccelTune / AccelBrain / iVIT | | | | |
| | Al Accelerator | | NVIDIA Qualcomm | | Intel | | |
| EDGE AI SYSTEM | APEX Series | | | | | | |
| KEY COMPONENT | Flash | DRAM | Display | Networking | Storage | Wi-Fi | |
| AND PERIPHERAL | VIOL. | | | | | (intel) | |
| | Camera Air Sensor | | | | ensor | | |
| SENSOR | • | | | | | 223 223 241 241 | |

INNOVATING WITH THE WORLD'S LEADING EDGE AI CORES

NVIDIA

The RTX Series AI accelerators deliver high-performance graphics, longevity, and versatile AI computing.

Qualcomm

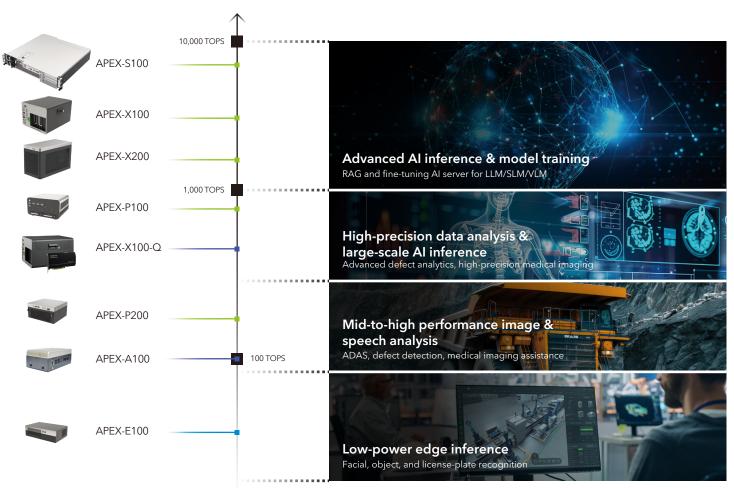
Cloud Al 100 Ultra accelerator for on premise LLMs; Dragonwing IQ Series for scalable edge Al.

Intel

Core Ultra processors with built-in NPUs deliver essential Al computing power;

Intel x86 platform offers compatibility for various use cases.

INNODISK EDGE AI SOLUTION LANDSCAPE



(TOPS @ INT8)

NVIDIA

| Model Name | APEX-S100 | APEX-X100 |
|--------------------------|--|--|
| Product Highlight | MGX AI modular server supporting NVIDIA data center accelerators for high-end AI model training | Supports NVIDIA professional-grade accelerators for lightweight AI training and complex inference |
| Al Accelerator | NVIDIA L40S RTX PRO 6000 Blackwell Server Edition Tesla H200 NVL Up to dual accelerator (varies by SKU) | NVIDIA RTX PRO 6000 Blackwell Max-Q / 96GB GDDR7 24,064 Cuda Cores 752 Tensor Cores 188 RT Cores NVIDIA RTX 6000 Ada / 48GB GDDR6 (Optional) |
| СРИ | - Intel Xeon 6731P - Intel Xeon 6730P - Intel Xeon 6736P | - Intel Core i9-13900E - Intel Core i7-13700E - Intel Core i9-14900 |
| Memory | Support up to DDR5 1TB (Up to 768GB pre-installed) (varies by SKU) | Support up to DDR5 192GB (64GB / 128GB / 192GB pre-installed) |
| Storage | Up to 2 × 2TB M.2 + 4 × 3.84TB E1.S pre-installed | 512GB / 1TB / 2TB pre-installed |
| Display | 1 × Mini DP | 1 × HDMI, 2 × DP++, *VGA |
| Ethernet | 2 × 10Gbps or 2 × 25Gbps or 2 × 200Gbps (varies by SKU) | - 1 × 10Gbps - 3 × 2.5Gbps (30W PoE × 2) |
| Expansion Slots | - 2 × M.2 2280 / 22110 M Key - 4 × E1.S - 2 × PCle ×16 (Gen 5 ×16)* - 1 × PCle ×16 (Gen 5 ×16) - 1 × PCle ×8 (Gen 5 ×16) | - 1 × M.2 3052 B Key - 1 × M.2 2280 M Key - 1 × M.2 2230 E Key - 2 × PCle ×16 (Gen 4 ×16)* - 1 × PCle ×16 (Gen 3 ×4) - 1 × PCle ×4 (Gen 3 ×4) - 1 × PCle ×1 (Gen 3 ×1) |
| External I/O | 2 × USB 2.0 | - 3 × COM - 1 × USB 3.2 Gen 2 ×2 (Type-C) - 8 × USB 3.2 Gen 2 ×1 - 1 × 8 bit GPIO |
| Features | Hot-swappable E1.S SSD & CRPS PSU | Out-of-band (OOB) |
| Power Input/Consumption | AC 220V | DC 24V (24V@19.8A) |
| Dimension (L x W x H/mm) | 438 × 420 × 88 | 340 × 279 × 215 |
| Operating Temperature | 0°C ~ 30°C | 0°C ~ 50°C |

| Place Bank | - THE REAL PROPERTY OF THE PARTY OF THE PART |
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| APEX-X200 | APEX-P100 | APEX-P200 | |
|--|---|---|--|
| Flexible and compact system design supporting a wide range of NVIDIA accelerators | Compact design supports MXM Type-B accelerators for lightweight Al inference | Ultra-compact 182 × 158.6 mm design supports MXM Type-A accelerators and operates from -20°C ~ 60°C | |
| - NVIDIA RTX 5080 / 16GB GDDR7 - 10,752 CUDA Cores - 336 Tensor Cores - 84 RT Cores | - NVIDIA RTX 5000 Ada /16GB GDDR6 - 9,728 Cuda Cores - 304 Tensor Cores - 76 RT Cores | NVIDIA RTX 2000 Ada / 8GB GDDR6 3,072 Cuda Cores 96 Tensor Cores 24 RT Cores NVIDIA RTX PRO 2000 Blackwell planning | |
| Intel Core Ultra 7 265 | Intel Core i7-13700E | Intel Core i7-13800HE | |
| Support up to DDR5 96GB (64GB pre-installed) | Support up to DDR5 64GB (32GB pre-installed) | Support up to DDR5 64GB (32GB pre-installed) | |
| 512GB pre-installed | 512GB pre-installed | 512GB pre-installed | |
| 1 × DP 2.1, 1 × HDMI 2.1 | 5 × DP++ | 1 × HDMI | |
| 2 × 2.5Gbps | 5 × 2.5Gbps | 3 × 2.5Gbps (30W PoE × 2) | |
| - 2 × M.2 2280 M key - 1 × M.2 2230 E key - 2 × PCIe ×16 (Gen 5 x16)* | - 2 × M.2 2280 M Key - 1 × MXM Type B/B+ (Gen 4 ×16) | - 1 × M.2 2280 M Key - 1 × M.2 2230 E Key - 1 × MXM Type A (Gen 4 ×8) | |
| - 4 × COM - 8 × USB 3.2 Gen 2 ×1 - 2 × USB 2.0 | - 4 × COM - 1 × USB 3.2 Gen 2 ×2 (Type-C) - 6 × USB 3.2 Gen 2 ×1 - 2 × USB 2.0 - 1 × 7 bit GPIO | - 2 × COM - 2 × USB 3.2 Gen 2 ×1 - 2 × USB 2.0 | |
| Out-of-band (OOB) | Out-of-band (OOB) | Out-of-band (OOB) | |
| FLEX ATX 850W PSU | DC 24V (24V@19.8A) | DC 19V (19V@10.5A) | |
| 381 x 185 x 235 | 280 × 270 × 148.2 | 182 × 158.6 × 90 | |
| 0°C ~ 45°C | 0°C ~ 50°C | -20°C ~ 60°C | |

Intel







| , | | |
|---|---|--|
| APEX-X100-Q | APEX-A100 | APEX-E100 |
| Supports Qualcomm AI 100 Ultra accelerator, ideal for LLM and SLM workloads | Featuring Qualcomm Dragonwing industrial-grade SoC for edge Al applications | Powered by Intel's latest design with built-in NPU for lightweight Al applications |
| - Qualcomm Cloud AI 100 Ultra - 870 TOPS (INT8) - 288 TFLOPS (FP16) | - 2 × Hexagon Tensor Processor NPU - 100 TOPS Dense (INT8) - 200 TOPS Sparse (INT8) | - Intel AI Boost via CPU + GPU + NPU - Up to 36 TOPS (INT8) |
| Intel Core i7-13700E | Qualcomm Dragonwing IQ-9075 | - Intel Core Ultra 7 165H - Intel Core Ultra 5 135H - Intel Core Ultra 3 105U |
| Support up to DDR5 192GB (192GB pre-installed) | 36GB LPDDR5X (on board) | Support up to DDR5 96GB (16GB pre-installed) |
| 2TB pre-installed | 128GB UFS pre-installed | 512GB pre-installed |
| 1 × HDMI, 2 × DP++, *VGA | 2 × DP1.2, 1 × eDP | 2 × HDMI |
| 1 × 10Gbps 3 × 2.5Gbps (30W PoE × 2) | 2 × 2.5Gbps | 2 × 2.5Gbps |
| - 1 × M.2 3052 B Key - 1 × M.2 2280 M Key - 1 × M.2 2230 E Key - 2 × PCle ×16 (Gen 4 ×16) - 1 × PCle ×16 (Gen 3 ×4) - 1 × PCle ×4 (Gen 3 ×4) - 1 × PCle ×1 (Gen 3 ×1) | - 1 × M.2 3052 B Key - 1 × M.2 2280 M Key - 1 × M.2 2230 E Key | - 1 × M.2 2280 M Key - 1 × M.2 2230 E Key |
| - 3 × COM - 1 × USB 3.2 Gen 2 ×2 - 8 × USB 3.2 Gen 2 ×1 - 1 × 8 bit GPIO | - 1 × COM - 3 × USB 3.2 Gen 2 ×1 - 1 × USB 3.2 Gen 2 ×1 (Type-C) - 2 × USB 2.0 - 1 × CAN FD | - 1 × COM - 2 × USB 3.2 Gen 2 ×1 - 2 × USB 3.2 Gen 1 ×1 - 2 × USB 2.0 |
| Out-of-band (OOB) | 2 × MIPI over FPC | 2 × MIPI over Type-C |
| DC 24-48V (24V@14A) | DC 9-36V (12V@2.6A) | DC 12V (12V@12.5A) |
| 340 × 279 × 215 | 180 × 108.7 × 69 | 188 × 140 × 56 |
| 0°C ~ 40°C | -40°C ~ 70°C | -20°C ~ 60°C |

TAILORED DESIGN & QUALITY MANUFACTURING

Backed by proven expertise and trusted global partnerships, Innodisk delivers a flexible collaborative approach that seamlessly integrates software, hardware, and firmware ensuring solutions tailored to your unique business needs.



Al Accelerators with diverse solutions



Flexibleproduct design and collaboration approach



Seamless integration capabilities



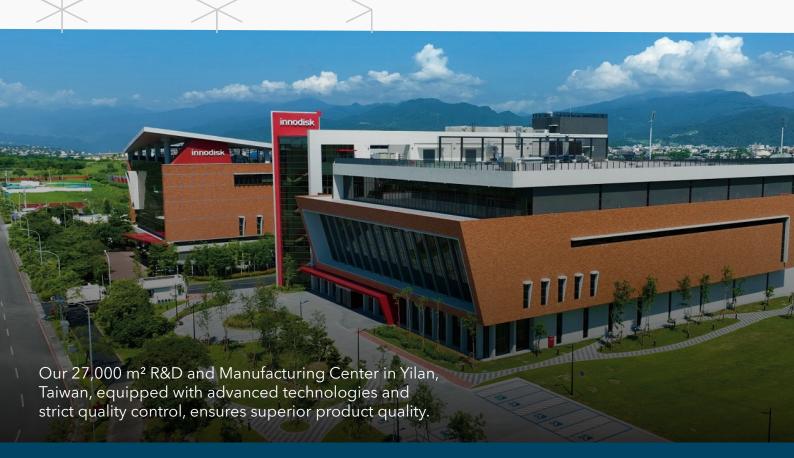
Expertise in vertical markets and applications



4,000+ global customer experience



Global technical and service network





ABOUT INNODISK

innodisk